Amendments to the Claims

Claim Listing

This claim listing replaces all previous versions and prior listings of the claims

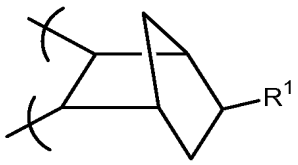
1. **(Currently Amended)** A composition comprising:

a polymer with a glass transition temperature greater than ~~250~~310°C and a water absorption of 2% or less;

one or more metals or metal compounds; and

an organic solvent;

wherein said polymer is a polynorbornene comprising molecular units of formula I



I

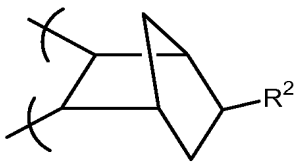
wherein R^1 is independently selected from hydrogen and a (C_1-C_{10}) alkyl.

2. – 4. **(Cancelled)**

5. **(Original)** The composition of claim 1 wherein the water absorption is 1% or less.

6. - .7 **(Cancelled)**

8. **(Currently Amended)** The composition of claim ~~7~~ 1 wherein the polymer is a polynorbornene that further comprises molecular units of formula II



II

wherein R^2 is a pendant group capable of participating in a cross-linking or network-forming reaction selected from the group consisting of ~~comprising~~: epoxides, alcohols, silyl ethers, carboxylic acids, esters, and anhydrides; and the molar ratio of molecular units of formula II to formula I is greater than 0 to about 0.4.

9. **(Cancelled)**

10. (**Original**) The composition of claim 1 wherein the polymer contains sites that can crosslink with one or more crosslinking agents.

11. (**Original**) The composition of claim 8 further comprising one or more crosslinking agents which includes polyhydroxystyrene.

12. (**Original**) The composition of claim 1 further comprising a metal adhesion promoter.

13. (**Original**) The composition of claim 12 wherein the metal adhesion promoter is selected from the group consisting of a phenoxy resin, polyhydroxyphenyl ether and 2-mercaptobenzimidazole.

14. (**Original**) The composition of claim 10 further comprising a hydroxyl-capping agent.

15. (**Original**) The composition of claim 14 wherein the hydroxyl-capping agent is a blocked isocyanate agent.

16. (**Currently Amended**) The composition of claim 1 wherein the composition is used to make an electronic component selected from the group consisting of resistors and discrete or planar capacitors.

17. (**Currently amended**) The composition of claim 16 wherein the electronic component is a resistor with a percent resistance change of less than ±5% with respect to the relative humidity test.

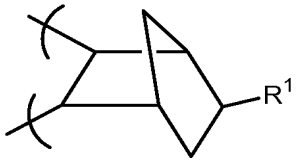
18. (**Currently amended**) The composition of claim 17 wherein the resistor exhibits a percent resistance change of less than ±1% with respect to an electrostatic discharge ~~ESD~~ test.

19. (**Currently amended**) The composition of claim 16 wherein the electronic component is a discrete or planar capacitor with a capacitance percent loss of less than 5%.

20. (**Original**) The composition of claim 1 wherein the composition is used to prepare a conductive adhesive.

21. (**Original**) The composition of claim 1 wherein the composition has a cure temperature of less than 180°C or can be cured at a peak temperature up to about 270°C with a short infrared cure.

22. (**Currently amended**) A composition comprising a polymer with a glass transition temperature greater than ~~250~~310°C and a water absorption of 2% or less, and an organic solvent wherein said polymer is a polynorbornene comprising molecular units of formula I



I

wherein R^1 is independently selected from hydrogen and a (C_1-C_{10}) alkyl.

23. (**Cancelled**)

24. (**Original**) The composition of claim 22 wherein the composition has a cure temperature of less than 180°C or can be cured at a peak temperature up to about 270°C with a short infrared cure, and the composition is used as an encapsulant or an integrated circuit and wafer-level package selected from semiconductor stress buffers, interconnect dielectrics, protective overcoats bond pad redistribution, or solder bump underfills.

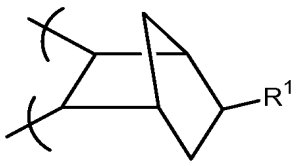
25. (**Currently Amended**) A method of making a PTF resistor comprising:

combining a polymer with a glass transition temperature greater than ~~250~~310°C and a water absorption of less than 2%, one or metals or metal compounds, and an organic solvent to provide a PTF resistor composition;

applying the PTF resistor composition to a substrate; and

curing the applied PTF resistor composition; and

wherein the polymer is a polynorbornene comprising molecular units of formula I



I

wherein R^1 is independently selected from hydrogen and a (C_1-C_{10})alky.

26. (**Cancelled**)

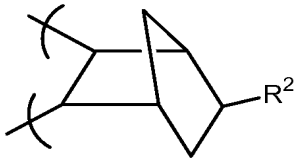
27. (**Original**) The method of claim 25 wherein the curing of the applied PTF resistor composition includes a cure temperature of less than 180°C or a peak temperature up to about 270°C with a short infrared cure.

28. (**Cancelled**)

29. (**Original**) The method of claim 25 wherein the polymer has a water absorption of 1% or less.

30. (**Cancelled**)

31. (**Currently Amended**) The method of claim ~~30~~25 wherein the polymer is a polynorbornene that further comprises molecular units of formula II



II

wherein R^2 is a crosslinkable epoxy group, and the molar ratio of molecular units of formula II to formula I is greater than 0 to about 0.4.

32. (**Cancelled**) ~~The method of claim 26 wherein the polymer is a polyarylate.~~

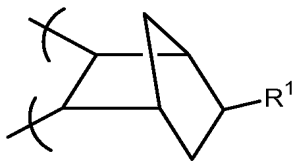
33. (**Currently Amended**) An electronic component selected from the group consisting of PTF resistors and discreet or planar resistors, wherein the electronic component comprises a cured composition prepared by a process comprising:

combining a polymer with a glass transition temperature greater than ~~250~~310°C and a water absorption of 2% or less, one or metals or metal compounds, and an organic solvent to provide an uncured composition;

applying the uncured composition to a substrate; and

curing the applied composition; and

wherein the polymer is a polynorbornene comprising molecular units of formula I



I

wherein R^1 is independently selected from hydrogen and a (C_1-C_{10})alky.

.